



STGW45HF60WD

45 A, 600 V ultra fast IGBT

Features

- Improved E_{off} at elevated temperature
- Low C_{RES} / C_{IES} ratio (no cross-conduction susceptibility)
- Ultra fast soft recovery antiparallel diode

Applications

- Welding
- High frequency converters
- Power factor correction

Description

The “HF” family is based on a new advanced planar technology concept to yield an IGBT with more stable switching performance (E_{off}) versus temperature, as well as lower conduction losses. The “W” series is a subset of products tailored to high switching frequency operation (over 100 kHz).

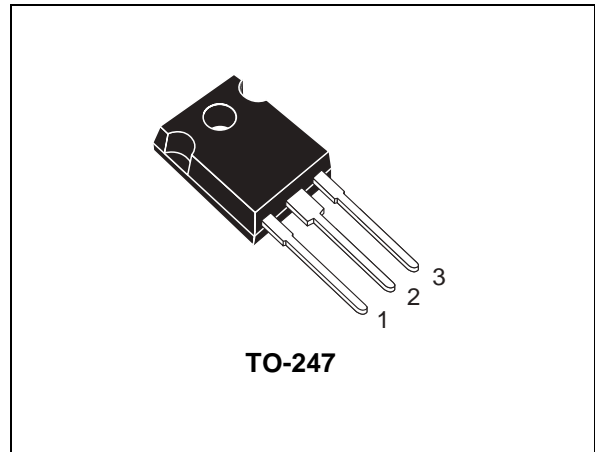


Figure 1. Internal schematic diagram

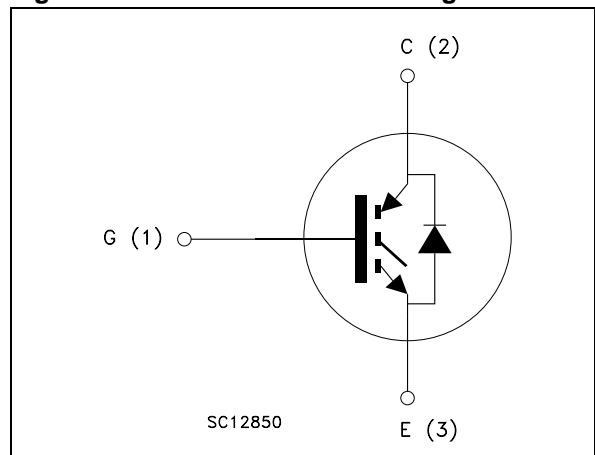


Table 1. Device summary ⁽¹⁾

Order code	Marking	Package	Packaging
STGW45HF60WD	GW45HF60WDA	TO-247	Tube
	GW45HF60WDB		
	GW45HF60WDC		

1. Collector-emitter saturation voltage is classified in group A, B and C, see [Table 5: VCE\(sat\) classification](#). STMicroelectronics reserves the right to ship from any group according to production availability.

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	600	V
$I_C^{(1)}$	Continuous collector current at $T_C = 25\text{ °C}$	70	A
$I_C^{(1)}$	Continuous collector current at $T_C = 100\text{ °C}$	45	A
$I_{CP}^{(2)}$	Pulsed collector current	150	A
$I_{CL}^{(3)}$	Turn-off latching current	80	A
V_{GE}	Gate-emitter voltage	± 20	V
I_F	Diode RMS forward current at $T_C = 25\text{ °C}$	30	A
I_{FSM}	Surge not repetitive forward current $t_p = 10\text{ ms}$ sinusoidal	120	A
P_{TOT}	Total dissipation at $T_C = 25\text{ °C}$	250	W
T_{stg}	Storage temperature	– 55 to 150	°C
T_j	Operating junction temperature		

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{j(max)} - T_C}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(max)}, I_C(T_C))}$$

2. Pulse width limited by maximum junction temperature and turn-off within RBSOA

3. $V_{CLAMP} = 80\% (V_{CES})$, $V_{GE} = 15\text{ V}$, $R_G = 10\text{ }\Omega$, $T_J = 150\text{ °C}$

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case IGBT	0.5	°C/W
	Thermal resistance junction-case diode	1.5	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient	50	°C/W